

EAST Search History

EAST Search History (Prior Art)

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|--|------------------|---------|---------------------|
| L1 | 2 | (*6,671,174*).FN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/12/03 10:12 |
| L2 | 2 | (*6,628,779*).FN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/12/03 10:29 |
| S1 | 1 | Modem adj module and carrier adj assembly and telephone adj line and solder adj pad | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 11:31 |
| S2 | 3234 | 375/222.ccls. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 11:32 |
| S3 | 1 | S2 and motherboard and solder adj pad and modem and connector and ring | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 11:33 |
| S4 | 1 | S2 and motherboard and solder adj pad and modem and printed adj circuit adj board | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 11:33 |
| S5 | 1 | S2 and motherboard and solder adj pad | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 11:34 |
| S6 | 15 | S2 and motherboard and modem and printed adj circuit adj board | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 11:34 |
| S7 | 1 | S6 and solder adj pad | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 11:34 |

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|-----|---------|--|--|----|----|---------------------|
| S8 | 2 | S6 and pad | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 11:34 |
| S9 | 5 | modem adj module and connector and motherboard and solder\$4 and connection | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 13:02 |
| S10 | 39 | modem adj module and connector and motherboard | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 13:51 |
| S11 | 4 | S10 and solder adj pads | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 13:51 |
| S12 | 8267373 | S10 and solder adj pads and MODEM MODULE MOUNT COMPRISE SOLDER PAD CONNECT | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 13:53 |
| S13 | 1 | S10 and solder adj pads and MODEM adj MODULE adj MOUNT and SOLDER adj PAD adj CONNECT | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 13:54 |
| S15 | 1 | solder adj pads and MODEM adj MODULE adj MOUNT and SOLDER adj PAD adj CONNECT | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 13:55 |
| S17 | 1 | circuitry adj interfac\$3 and connecting adj modem and module adj carrier | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 14:06 |
| S19 | 0 | circuitry adj interfacin and connection and carrier | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 15:54 |
| S20 | 87890 | circuitry and connection and carrier | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 15:56 |

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| S21 | 3234 | 375/222.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 16:26 |
| S22 | 1 | S21 and motherboard and solder adj pad and modem and printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 16:26 |
| S23 | 1 | S21 and solder adj pad and modem and circuitry and printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 16:28 |
| S24 | 1 | S21 and solder adj pad and modem and circuitry | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 16:29 |
| S25 | 865 | S21 and modem and circuitry | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 16:30 |
| S26 | 60 | S25 and printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 16:31 |
| S27 | 42 | S21 and circuitry and motherboard | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 16:37 |
| S28 | 240 | circuitry adj interfac\$3 and modem and printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 17:46 |
| S29 | 2 | S28 and solder adj pads | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 17:46 |
| S30 | 2501554 | Motherboard ro Printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:07 |

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| S31 | 4317 | S30 and solder adj pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:07 |
| S32 | 1 | S31 and modem adj assembly | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:08 |
| S33 | 25 | S30 and modem adj assembly | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:08 |
| S34 | 1 | S33 and solder adj pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:09 |
| S35 | 22657 | S30 and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:11 |
| S36 | 142 | S35 and solder adj pads | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:11 |
| S37 | 98 | S36 and PCB | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:12 |
| S38 | 30 | S37 and telephone adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/19 18:12 |
| S39 | 283029 | printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 10:23 |
| S40 | 122 | S39 and modem adj circuitry | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 10:23 |

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| S41 | 9 | S40 and solder adj pads | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 10:24 |
| S42 | 9 | S41 and telephone | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 10:24 |
| S43 | 9 | S41 and telephone adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 10:24 |
| S44 | 2 | S43 and ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 10:25 |
| S45 | 32 | "4573753" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 11:53 |
| S46 | 2 | ("4573753").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/06/20 11:54 |
| S47 | 0 | "input/output or I/O device" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:02 |
| S48 | 0 | ("input/output or I/O device").CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/06/20 12:02 |
| S49 | 0 | "input/output or I/O device" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:02 |
| S50 | 0 | "input/output or I/O device" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:03 |

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| S51 | 46033 | "input/output device" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:03 |
| S52 | 1545 | S51 and motherboard | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:26 |
| S53 | 694 | S52 and slots | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:26 |
| S54 | 13 | S53 and "I/O cards" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:27 |
| S55 | 33982 | motherboard | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:36 |
| S56 | 10528 | S55 and slots | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:36 |
| S57 | 312 | S56 and "I/O cards" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:36 |
| S58 | 24 | S57 and receptacle | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 12:40 |
| S59 | 1 | "11416757" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 13:09 |
| S60 | 8 | "5788509" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/06/20 14:49 |

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| S61 | 2 | ("5788509").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/06/20 14:49 |
| S62 | 2 | ("5990981").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/06/20 14:50 |
| S63 | 2 | ("5,519,573").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/06/20 14:52 |
| S64 | 2 | ("6,752,665").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/06/20 16:25 |
| S65 | 3 | "US 20020076038" | US-PGRUB; USPAT; USOCR; DERWENT | OR | ON | 2009/07/31 15:10 |
| S66 | 9 | ("2002/0076038").URPN. | USPAT | OR | ON | 2009/07/31 15:10 |
| S67 | 2 | ("4,766,402").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/07/31 15:12 |
| S68 | 2 | fabricating near3 modem near4 module | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:13 |
| S69 | 7697 | modem near4 module | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:14 |
| S70 | 2 | S69 and motherboard and solder adj pad and modem and connector and ring | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:14 |
| S71 | 6 | S69 and motherboard and solder adj pad and modem | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:15 |

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| S72 | 6 | S69 and motherboard and solder adj pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:16 |
| S73 | 9 | S69 and motherboard and solder and signal adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:16 |
| S74 | 109 | fabricating near3 modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:18 |
| S75 | 1 | S74 and solder and signal adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:18 |
| S76 | 2 | S74 and motherboard and solder adj pad and modem and connector and ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:19 |
| S77 | 2 | S74 and motherboard and solder and modem and connector | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:20 |
| S78 | 2 | S74 and motherboard and modem and connector | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:20 |
| S79 | 2 | S74 and motherboard and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:20 |
| S80 | 6737 | modem and circuitry and printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:22 |
| S81 | 100 | S80 and solder adj pad and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:23 |

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|-----|--------|---|--|----|-----|---------------------|
| S82 | 19 | method near4 fabricating near4 modem | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:23 |
| S83 | 4 | S81 and S82 | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/31 15:23 |
| S84 | 5 | ("2002/0172969").URFN. | USPAT | OR | ON | 2009/07/31 15:25 |
| S85 | 2 | "US 20050190824" | US-PGRUB; USPAT; USOCR; DERWENT | OR | ON | 2009/07/31 15:53 |
| S86 | 2 | "US 20090016040" | US-PGRUB; USPAT; USOCR; DERWENT | OR | ON | 2009/08/03 09:51 |
| S87 | 2 | ("4767344").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/08/03 09:59 |
| S88 | 2 | ("4,767,344").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/08/03 11:31 |
| S89 | 2 | ("6,078,661").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/07/05 08:53 |
| S90 | 127399 | Carrier same assembly | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:55 |
| S91 | 1184 | S90 and telephone same line | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:55 |
| S92 | 3 | S91 and "tip/ring" | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:56 |
| S93 | 16 | S91 and integrated same device and modem and printed adj circuit adj board | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:58 |

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| S94 | 1 | S93 and "tip/ring" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:58 |
| S95 | 1 | S89 and tip same ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:58 |
| S96 | 1 | S89 and tip same4 ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:59 |
| S97 | 1 | S89 and tip and ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:59 |
| S98 | 1 | S89 and ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:59 |
| S99 | 6 | S91 and integrated same device and modem and printed adj circuit adj board and pads | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 08:59 |
| S100 | 2 | S89 and ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:00 |
| S101 | 1 | S89 and connector and tip same ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:01 |
| S102 | 6 | S91 and integrated same device and modem and printed adj circuit adj board and pads | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:02 |
| S103 | 6 | S102 and telephone | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:02 |

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| S104 | 2 | S103 and ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:02 |
| S105 | 2 | S103 and tip | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:03 |
| S106 | 0 | ("2005/0190824").URFN. | USPAT | OR | ON | 2010/07/05 09:03 |
| S107 | 74 | solder adj pads and integrated same device and modem and printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:05 |
| S108 | 17 | S107 and modem and signal adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:06 |
| S109 | 1 | S108 and telephone adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:07 |
| S110 | 4 | S108 and telephone | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:07 |
| S111 | 2 | ("5,015,813").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/07/05 09:12 |
| S112 | 150 | signal same line and solder same pads and integrated same device and modem and printed adj circuit adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:14 |
| S113 | 31 | S112 and connector same interface and modem and solder same pads | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:15 |
| S114 | 2 | S113 and signal same line same connect\$4 with solder same pads | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/05 09:17 |

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| S115 | 2 | ("20050141206").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/07/05 09:20 |
| S116 | 2 | ("6,078,661").PN. | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/07/05 09:45 |
| S117 | 2 | "US 20050190824" | US-PGRUB; USPAT; USOCR; DERWENT | OR | ON | 2010/07/12 10:23 |
| S118 | 0 | ("2005/0190824").URPN. | USPAT | OR | ON | 2010/07/12 10:23 |
| S119 | 56581 | "Tip/ring" or "telephone line" or "ground side" or "positive" and "Ring or "battery" or "negative and "phone circuit" | USPAT | OR | ON | 2010/07/12 10:25 |
| S120 | 8823 | Tip near2 ring and "telephone line" or "ground side" or "positive" and "Ring or "battery" or "negative and "phone circuit" | USPAT | OR | ON | 2010/07/12 10:26 |
| S121 | 79 | S120 and solder same pad | USPAT | OR | ON | 2010/07/12 10:29 |
| S122 | 4 | S121 and tip same ring same connector | USPAT | OR | ON | 2010/07/12 10:31 |
| S123 | 7845 | tip same ring same lines | USPAT | OR | ON | 2010/07/12 10:53 |
| S124 | 0 | S123 and solder same pad and modem same module and tip same ring same connector and carrier | USPAT | OR | ON | 2010/07/12 10:57 |
| S125 | 2954 | S123 and Tip near2 ring and "telephone line" | USPAT | OR | ON | 2010/07/12 10:58 |
| S126 | 43 | S125 and circuitry near2 interfacing | USPAT | OR | ON | 2010/07/12 10:59 |
| S127 | 11 | S126 and telephone same line and integrated same device | USPAT | OR | ON | 2010/07/12 11:01 |
| S128 | 0 | S122 and motherboard | USPAT | OR | ON | 2010/07/12 14:51 |
| S129 | 10 | S126 and motherboard | USPAT | OR | ON | 2010/07/12 14:51 |
| S130 | 4 | S127 and S129 | USPAT | OR | ON | 2010/07/12 14:51 |
| S131 | 14 | S123 and printed adj circuit adj board near2 motherboard | USPAT | OR | ON | 2010/07/12 15:43 |

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|------|------|---|--|----|----|------------------|
| S132 | 0 | S131 and solder same pads | USPAT | OR | ON | 2010/07/12 15:44 |
| S133 | 5665 | S131 and Tip near2 ring and "telephone line" or "ground side" or "positive" and "Ring or "battery" or "negative and "phone circuit" | USPAT | OR | ON | 2010/07/12 15:45 |
| S134 | 14 | S131 and Tip near2 ring | USPAT | OR | ON | 2010/07/12 15:45 |
| S135 | 13 | S134 and "telephone line" | USPAT | OR | ON | 2010/07/12 15:45 |
| S136 | 82 | Modem adj module and telephone adj line and pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/16 14:25 |
| S137 | 13 | S136 and motherboard and "RJ11" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/16 14:26 |
| S138 | 0 | ("2005/0190824").URPN. | USPAT | OR | ON | 2010/07/16 14:27 |
| S139 | 322 | Modem adj module and telephone adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/16 14:28 |
| S141 | 136 | S139 and (tip or ring) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/16 14:28 |
| S142 | 44 | S141 and Modem same module and telephone adj line and pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/07/16 14:29 |
| S143 | 2 | ((BRAD) near2 (GRANDE)). INV. | USPAT | OR | ON | 2010/09/09 11:10 |
| S144 | 5 | ("4008427" "5799069" "5995381" "6212226" "6624635").FN. OR ("7499539").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:13 |
| S145 | 2 | "US 20050190824" | US-PGPUB; USPAT; USOCR; DERWENT | OR | ON | 2010/09/09 11:15 |
| S146 | 1 | ("modem assembly") with solder same pads and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:19 |
| S147 | 1 | ("modem") with solder same pads and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:20 |

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| S148 | 5 | ("modem") with solder and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:20 |
| S149 | 0 | ("modem") with solder near10 connect\$2 same signal and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:24 |
| S150 | 0 | ("modem") with solder near10 connect\$2 same signal and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:24 |
| S151 | 0 | ("modem") with solder near10 connector same signal and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:24 |
| S152 | 0 | ("modem") with solder near10 connecting same signal and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:25 |
| S153 | 0 | ("modem") with solder same pads near10 connecting same signal and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:25 |
| S154 | 0 | ((modem) with (solder same pads) near10 connecting same signal and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:26 |
| S155 | 4 | ((modem) with (solder same pads)) | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:26 |
| S156 | 0 | S155 and connecting same signal and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:26 |
| S157 | 1 | S155 and signal and tip and ring | US-PGPUB; USPAT; USOCR | OR | ON | 2010/09/09 11:27 |
| S158 | 2 | ("7499539").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/11/23 08:41 |
| S159 | 2 | ("7773733").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/11/23 08:43 |
| S160 | 1 | ((RODNEY) near2 (MEHLANDLER)).INV. | US-PGPUB; USPAT | OR | ON | 2010/11/23 08:44 |
| S161 | 6 | ((BRAD) near2 (GRANDE)).INV. | US-PGPUB; USPAT | OR | ON | 2010/11/23 08:45 |
| S162 | 46753 | Modem same module | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 08:58 |
| S163 | 9567 | S162 and telephone same line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 08:59 |

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| S164 | 29 | S163 and solder same pads | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 08:59 |
| S165 | 55 | S163 and ("tip/ring") | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:00 |
| S166 | 2 | S165 and solder same pads | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:00 |
| S167 | 3 | S165 and solder | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:00 |
| S168 | 13 | ("3239612" "3497639" "3515820" "3692961" "3692962" "3700830" "4021624" "4255025" "4255625").PN. OR ("4852144").URPN. | US-PGRUB; USPAT; USOCR | OR | ON | 2010/11/23 09:02 |
| S169 | 6154 | S163 and (motherboard Pcb board carrier) | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:12 |
| S170 | 29 | S169 and solder same pads | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:12 |
| S171 | 43 | S169 and ("tip/ring") | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:13 |
| S172 | 3 | S171 and solder | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:13 |
| S173 | 46753 | Modem same module | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:14 |

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| S174 | 4403 | S173 and modem same circuitry | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:14 |
| S175 | 1980 | S174 and (motherboard board PCB) | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:14 |
| S176 | 4 | S175 and ("tip/ring") | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:15 |
| S177 | 1 | S176 and pads | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:24 |
| S178 | 553 | S175 and pads | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:25 |
| S179 | 1 | S178 and ("tip/ring") | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:25 |
| S180 | 553 | S175 and pad | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:25 |
| S181 | 553 | S178 and pads | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:25 |
| S182 | 1 | S181 and ("tip/ring") | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:26 |
| S183 | 68 | S178 and solder | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:26 |

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|------|------|---|--|----|----|---------------------|
| S184 | 1 | S183 and ("tip/ring") | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:26 |
| S185 | 114 | (motherboard Pcb board carrier) and ("tip/ring") and pads | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:31 |
| S186 | 56 | S185 and telephone same line | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:32 |
| S188 | 225 | (card modem) with (solder \$3 adj pad) | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:42 |
| S189 | 2 | S188 and ("tip/ring") | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:43 |
| S190 | 6025 | tip near ring and telephone near5 line | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:44 |
| S191 | 6025 | (tip near ring) and (telephone near5 line) | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:44 |
| S192 | 2 | S188 and S191 | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:44 |
| S193 | 3 | S188 and (telephone near5 line) | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 09:45 |
| S194 | 155 | 361/760,767.ccls. and (solder adj pad) with (surface carrier board) | US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:16 |

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| S195 | 0 | S194 and rj11 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:16 |
| S196 | 155 | S194 and (pad terminal land electrode contact) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:17 |
| S197 | 0 | S196 and Tip near ring | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:17 |
| S198 | 39 | S196 and (connector) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:18 |
| S199 | 6 | S196 and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:18 |
| S200 | 1 | S199 and (connector) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:19 |
| S201 | 6 | S194 and (pad terminal land electrode contact)and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:20 |
| S202 | 6 | S194 and (pad terminal land electrode contact)and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:24 |
| S203 | 0 | 361/760,767.ccls. and RJ11 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:25 |
| S204 | 1429 | 361/760,767.ccls. and (Tip ring connector) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:25 |

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| S205 | 64 | S204 and (solder adj pad) with (surface carrier board) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:25 |
| S206 | 1 | S205 and (pad terminal (and electrode contact) and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:25 |
| S207 | 0 | S196 and telephone adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:32 |
| S208 | 6 | 361/760,767.cds. and telephone adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:33 |
| S209 | 88 | 361/760,767.cds. and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:39 |
| S210 | 76 | S209 and (pad terminal (and electrode contact) and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:39 |
| S211 | 6 | S210 and (solder adj pad) with (surface carrier board) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:39 |
| S212 | 0 | S211 and (RJ11) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:39 |
| S213 | 1 | S211 and connector | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:39 |
| S214 | 84 | (solder adj pad) with (surface carrier board) and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:41 |

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| S215 | 84 | (solder adj pad) with (surface carrier board)and modem and (pad terminal land electrode contact)and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:41 |
| S216 | 5276064 | (solder adj pad) with (surface carrier board)and modem and (pad terminal land electrode contact)and modemand (Tip ring connector) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:42 |
| S220 | 84 | (solder adj pad) with (surface carrier board)and modem and (pad terminal land electrode contact)and modem | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:42 |
| S221 | 8 | (solder adj pad) with (surface carrier board)and modem and (pad terminal land electrode contact)and modem and telephone adj line | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 10:43 |
| S222 | 1 | ("2002/0001979").URPN. | USPAT | OR | ON | 2010/11/23 12:47 |
| S223 | 8158 | (printed circuit board) with telephone near line | USPAT | OR | ON | 2010/11/23 13:32 |
| S224 | 1692 | S223 and tip near ring | USPAT | OR | ON | 2010/11/23 13:32 |
| S225 | 1 | S224 and (solder adj pad) with (surface carrier board) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/11/23 13:32 |
| S226 | 8 | ("4466688" "5457593" "5653601" "6083032" "6382989" "6560126"). PN. OR ("6671174").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2010/11/23 13:56 |
| S227 | 2 | "US 20080240425" | US-PGPUB; USPAT; USOCR; DERWENT | OR | ON | 2010/11/24 09:49 |
| S228 | 2 | "US 20080226081" | US-PGPUB; USPAT; USOCR; DERWENT | OR | ON | 2010/11/24 09:59 |

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